# **Table of Contents**



Sony IMX071 16.2 Mp, 4.8 μm Pixel Size APS-C (DX Format) CMOS Image Sensor from Nikon D7000

Module 3: Planar Pixel Analysis

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IPR-1011-804-03 21149JMRFER Revision 1.0 Published: December 23, 2010 2



## Table of Contents (all Modules)

- Module 1: Overview
  - Introduction, Device Summary, Product Teardown, Die Photograph, Die Features
- Module 2: Die Utilization, Basic Functionality Analysis
  - Annotated Metal 1 Die Photograph, Die Utilization Analysis, Standard Logic Cell Size, SRAM Cell Size
- Module 3: Planar Pixel Analysis
  - Pixel Design Summary, Pixel Schematic, Pixel Bevel SEM Analysis, Related Horizontal Pixel Dimensions
- Module 4: Pixel Cross-Sectional Analysis
  - Pixel Process Summary, Pixel Horizontal and Vertical Cross-Sectional SEM Analysis, TEM Analysis of a Pixel Transistor and Gate Oxide, Related Pixel Dimensions
- Module 5: Substrate Dopant Analysis
  - Pixel Bevel SCM Analysis, Pixel Cross-Sectional SCM Analysis, SRP of Pixel Substrate, SRP and SCM Analyses of Peripheral Substrate
- Module 6: Peripheral Cross-Sectional and Process Analysis
  - SEM and TEM Analyses of General Structure, Dielectrics, Metals, Vias and Contacts, Column Capacitors, MOS Transistors, Isolation, Results of SEM and TEM EDS Analyses (BSI Process Features if Present)



#### **Module 3 Contents**

- Active Pixel Design
- Pixel Schematic
- Die Edge Tilt View
- Microlenses Overview (Plan and Tilt View)
- Microlenses Detail (Plan and Tilt View)
- Color Filter Array
- Pixel Bevel Overview
- Pixels at Metal 3
- Pixels at Metal 2/Via 2
- Pixels at Metal 1/Via 1
- Pixels at Poly
- Pixels at Diffusion
- Shielded Pixels
- Statement of Measurement Uncertainty and Scope Variation
- About Chipworks





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